

ABSTRACT OF THE DISCLOSURE

A process for machining a wafer-like workpiece between two plates, in which material is abraded from the workpiece under the influence of an auxiliary substance supplied and of ^{28.05.03 Hz} pressure ^{28.05.03 Dm} ~~a weight~~ acting on the workpiece. In this process, the ~~load~~ ^{pressure} ^{28.05.03 Dm} on the workpiece ~~from the weight~~ is significantly reduced and ^{28.05.03 Hz} then increased again at least once during the machining of the workpiece, and the supply of the auxiliary substance is ^{28.05.03 Dm} ^{28.05.03 Hz} reduced as the ~~weight~~ ^{pressure} is increased.